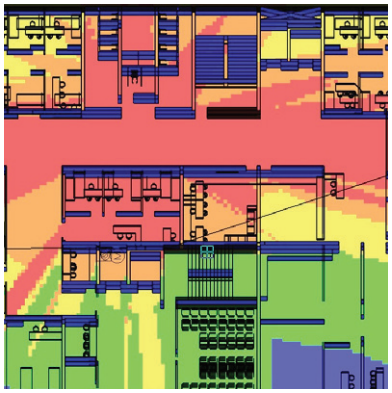
EDX WIRELESS

Next Generation Wireless Design

DAS Design Module

A POWERFUL ADD-ON MODULE THAT ENABLES BOTH INDOOR AND OUTDOOR DAS SYSTEMS TO BE DESIGNED AND VISUALIZED IN SIGNALPRO®

The DAS Design Module supports detailed design of indoor RF DAS and AP based integrated networks as well as outdoor campus and metro DAS networks. In addition to indoor and outdoor propagation models, the platform also contains asset management features that allow you to plan components, cables, antennas, connectors and other equipment and produce a bill of materials for your network.



Streamlined Floor Plan Import

Import AutoCAD .dwg files and tag walls and other objects of interest with their relevant RF material and height parameters.

Automated Floor Plan Conversion

Floor plan image files such as .jpg may be imported and automatically vectorized.

Multiple Floor/Building Designs

Each project may contain multiple buildings and floors with a 3D viewer depicting equipment layout and prediction performance for each floor.

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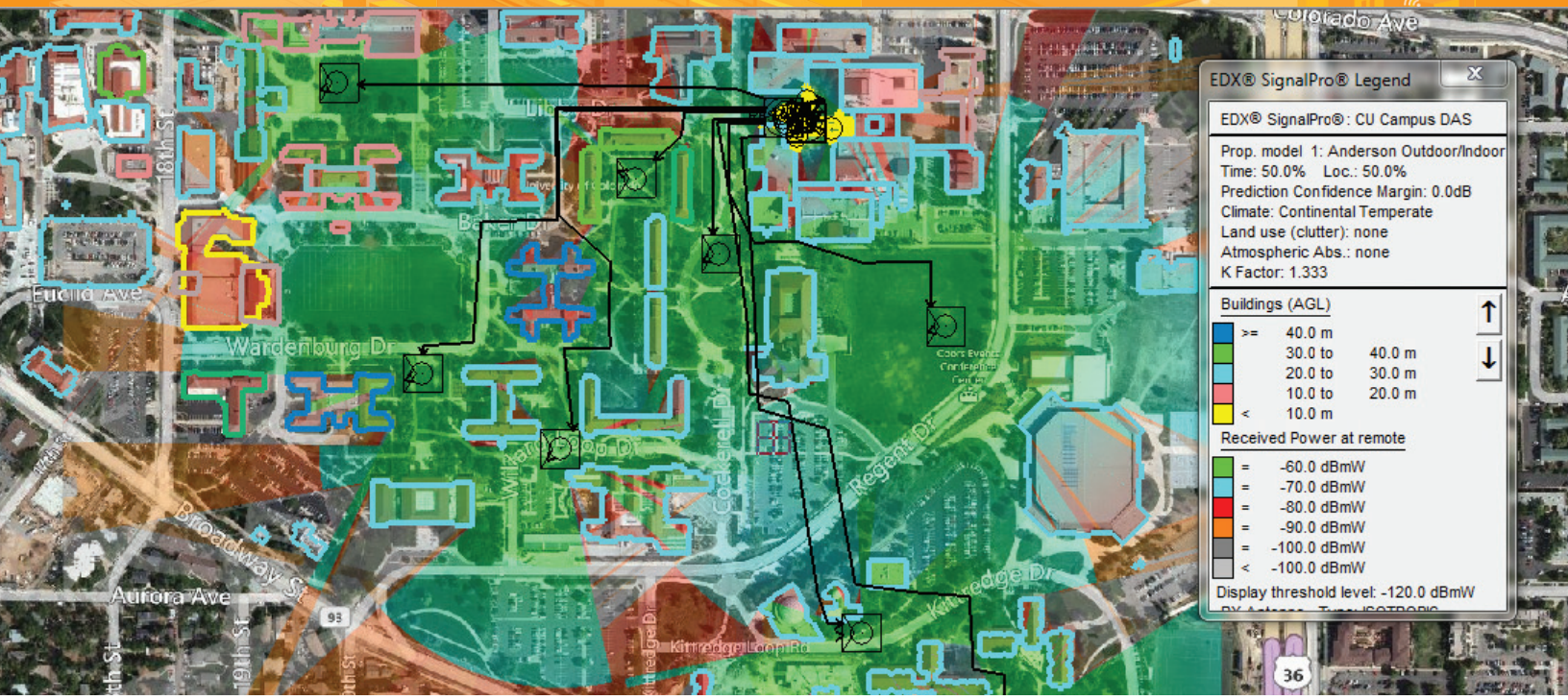

RF Equipment Library

The DAS Module comes with an editable library of RF equipment containing many common components that can be placed, moved and edited in a project or floorplan. The library fully supports user defined components as well.

Inter-Floor Cable Connections

The graphical riser tool allows for easy interconnection of RF and DAS cables between floors with automatic calculations of cable lengths and loss.

Schematic View

Display only the RF components and interconnecting cables with cable lengths and calculated RF power levels shown.

Query Tools

Powerful study query tools allow users to determine statistics across a service area.

A Simple Design Workflow

1. Import DWG or floor plan image file
2. Add RF components
3. Add risers between floors
4. Calculate and display RF coverage and performance
5. Model outdoor penetration into building and use for interference analysis
6. Document the DAS design with automatic report generation for bill of materials, RF-interconnection plots, RF link budget and study query reports